



PulseForge[®] Debonding Semi-Automatic Platform PD300SA



PulseForge semi-automated photonic debonding solution enables debonding through the use of a high-intensity flash lamp and a proprietary light absorbing layer coated carrier.

- Complete automation of the stage movement and synchronization with flash lamp processing
- Storable process flow protocol
- Digitally adjustable process conditions
- Accommodates up to 300 mm wafers on tape frame
- Interchangeable fixtures allow quick reconfiguration for different wafer sizes
- Ability to debond panels of up to 400 mm x 400 mm
- Capable of processing up to 20 wafers per hour
- Secured and interlock- controlled light shielding
- Patented water cooling to prevent heat build- up



PulseForge[®] PD300SA

Configuration

- Flash head that includes
 - 150 mm x 75 mm illumination area per pulse
 - Reflector housing
 - Water cooled flash lamp
 - Lamp change capability
 - Integrated protective window
 - Window removal mechanism
 - Adjustable air movement across window
- Controls rack containing
 - Capacitor banks
 - Power supply
 - Control module
 - Integrated display and controls
 - Keyboard
 - Integrated DI water chiller
- Optional site water connections for high duty cycle applications
- Umbilical connection between control rack and wafer handler for independent movement and up to 2 m distance in setup
- Accessible exhaust port for process chamber
- Photodiode processor box and software signal for pulse shape feedback
- Compressed air hose
- Standalone NIST-traceable integrated bolometer for pulse energy measurements
- Standard thermal simulation software – SimPulse[®]
- Standard 1 year warranty
- Optional extended warranty and service agreements are available upon request

Safety

- CE compliant
- Complete light shielding
- On-screen status indicators
- Temperature indicators on critical components
- Optional seismic feet

Parts Handling

PD300SA is configured to process up to 300 mm diameter standard wafers or up to 400 mm x 400 mm panels

- Configurable for 300mm, 250 mm, 200 mm and 150 mm standard wafer sizes¹
- Manual load and unload of the wafer pairs
- Fully automated x-y stage to eliminate any handling of wafer during processing
- Vacuum enabled sample stage for processing to reduce movement of parts
- Adjustable stage height to accommodate different thickness device structures

Flash Head Radiative Performance

Single Pulse illumination area	112 cm ²
Peak incident power	40 kW/cm ²
Maximum single pulse energy	70 J/cm ²
Maximum average power output	15 W/cm ²
Exposure uniformity	> 95%

Facility Requirements

Electric supply	Required
200 V – 240 V (-US)	3 Ø, 45 A
380 V – 420 V (-EU)	3 Ø, 25 A
Dry compressed air	
Pressure	200 – 1400 kPa
Flow rate	140 standard LPM
Site cooling water	Optional
Temperature	15 – 20C
Flow rate	25 LPM
Exhaust connection	75 mm (3") connection
Flow rate	Up to 500 cfm

Manufacturer Information

PulseForge Inc.
400 Parker Dr, Suite 1110
Austin, TX 78728
United States of America
Email: pf.sales@pulseforge.com
Phone: +1-512-491-9500 ext. 245

¹ Smaller wafer sizes can be handled upon request.